



Docket No.: 20135-00315-US
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

James W. Heater, et al

Application No.: 09/619,701

Group Art Unit: 3729

Filed: July 19, 2000

Examiner: A. Tugbang

For: UNIVERSAL TOOL FOR UNIFORMLY
APPLYING A FORCE TO A PLURALITY OF
COMPONENTS ON A CIRCUIT BOARD

AMENDMENT

Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated December 3, 2002 (Paper No. 7), please amend the above-identified U.S. patent application as follows:

IN THE ABSTRACT:

Kindly replace the Abstract with the attached new Abstract.

IN THE CLAIMS:

Kindly amend claim 11 as follows:

11. (Amended) A method for applying a bonding pressure to circuit board components being bonded to a circuit board comprising:

supporting first, second and third pressure cylinders over components on said circuit board along one of first and second axes, each of said pressure cylinders having foot which extends under air pressure against said components; and

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